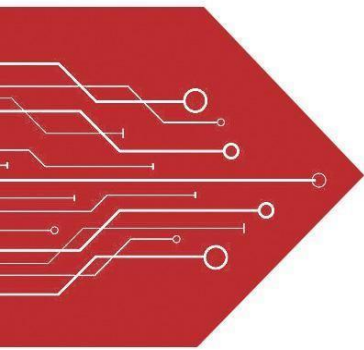


MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

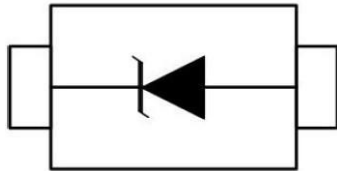


PLED

Product data sheet

www.msksemi.com

- ◆ 350 Watts peak pulse power (tp = 8/20µs)
- ◆ Transient protection for high speed data lines to IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns)
- ◆ Working voltages : 3.3V-36V
- ◆ Protects one bidirectional line
- ◆ Low operating and clamping voltages
- ◆ Solid-state silicon avalanche technology



SOD-323

Applications

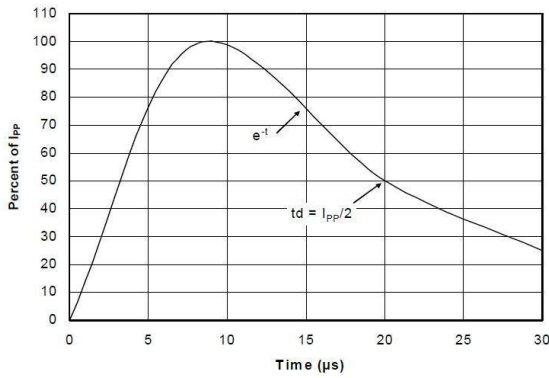
- ◆ Notebooks, Desktops, Servers and Video Graphics Cards
- ◆ USB Power & Data Line Protection
- ◆ Monitors and Flat Panel Displays
- ◆ I²C Bus Protection
- ◆ Portable Instrumentation
- ◆ Set Top Box

Symbol	Parameter	Value	Units
V _{ESD}	ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	±15 ±8	kV
P _{PP}	Peak Pulse Power (8/20µs)	350	W
T _{OPT}	Operating Temperature	-55/+150	°C
T _{STG}	Storage Temperature	-55/+150	°C
T _L	Lead Soldering Temperature	260 (10 sec.)	°C

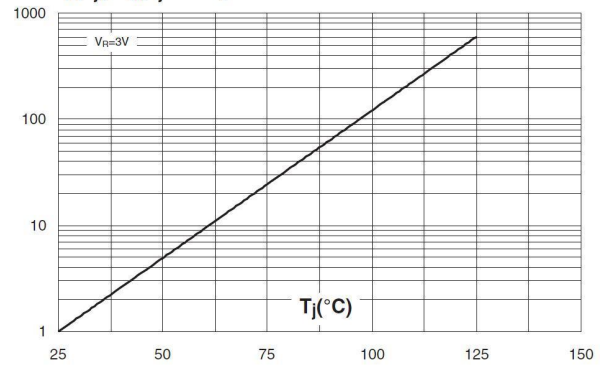
P/N	V _{RWM} (V) (max.)	V _B (V) (min.)	I _T (mA)	V _{C@1A} (V) (max.)	V _C (V) (max.) (@A)	I _R (μA) (max.)	C _T (pF) (max.)
ESD3Z5.0T1G-MS	5	6	1	9.8	18 17	10	300

Typical Characteristics @ Ta=25°C unless otherwise specified

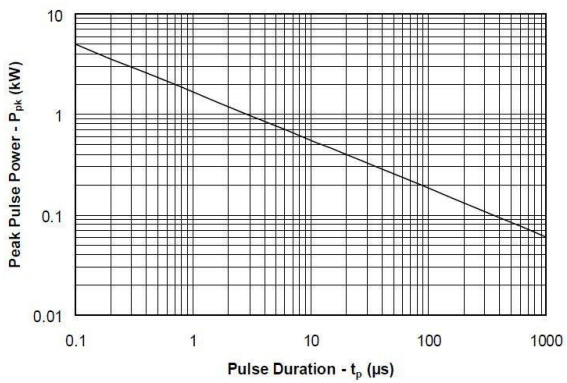
Pulse Waveform



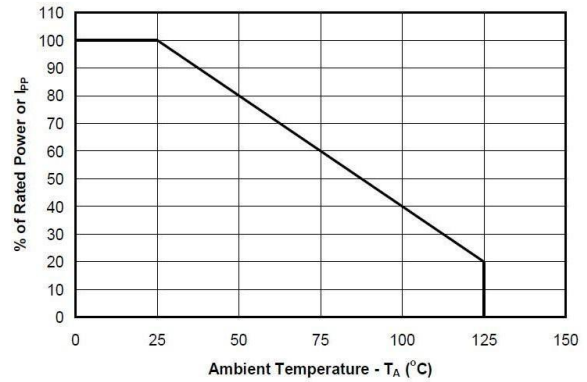
I_R[T_J] / I_R[T_J=25°C]



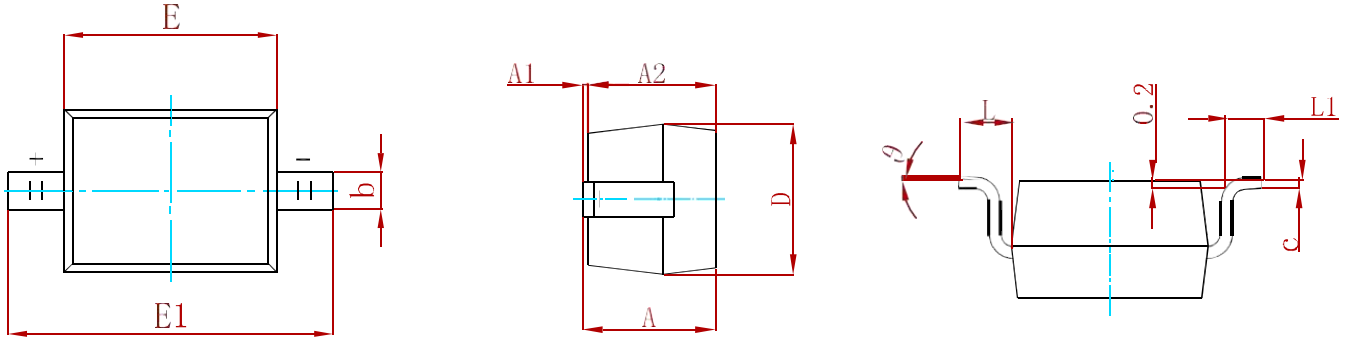
Non-Repetitive Peak Pulse Power vs. Pulse Time



Power Derating Curve

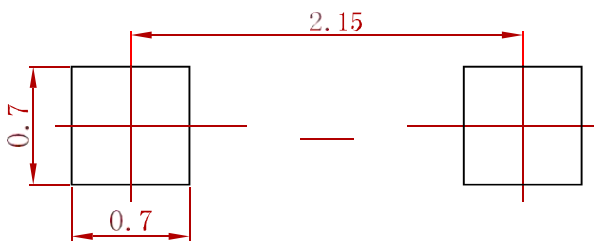


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESD3Z5.0T1G-MS	SOD-323	3000

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